

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|--|---|------------------|---------|------------------|
| L1 | 251240 | (flexible bent bentable bending bented) with (layer substrate carrier board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/16 18:33 |
| L2 | 41515 | (die chip ic electronic (integrated adj circuit) semiconductor) same 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/16 18:35 |
| L3 | 8960 | (resilient metal stiff stiffen stiffening resiliently) same 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/16 18:37 |
| L4 | 2498 | 3 same (trace wiring wire) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/16 18:38 |
| L5 | 971 | 4 and (package packaged packaging) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/16 18:38 |